

# LINEAR TECHNOLOGY MATERIALS DECLARATION

LTC6655CHMS8-4.09#PBF

(Engineering Calculation)

MSOP

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TOTAL MASS (g):

0.02801803

COMPONENT MATERIAL	VENDOR/ INDUSTRY NAMES	CONSTITUENT NAME	CAS NUMBER	CONSTITUENT MASS (g)	CONSTITUENT (PPM) OF MATERIAL	CONSTITUENT (PPM) OF TOTAL PKG.		
Active Device	Linear Technology	Silicon (Si)	7440-21-3	0.002529	1000000	90263.31		
Die Coat	Dow Corning	Silicone	67762-90-7	0	0	0		
Lead Frame	Cu	Copper (Cu)	7440-50-8	0	0	0		
		Iron (Fe)	7439-89-6	0.006206	580000	221500.3		
		Phosphorus (P)	7723-14-0	0	0	0		
		Zinc (Zn)	7440-66-6	0	0	0		
		Nickel (Ni)	7440-02-0	0.004494	420000	160396.8		
		Silicon (Si)	7440-21-3	0	0	0		
		Magnesium (Mg)	7439-95-4	0	0	0		
		Tin (Sn)	7440-31-5	0	0	0		
		<b>Lead Frame Total:</b>				<b>0.0107</b>	<b>1000000</b>	<b>381897</b>
Plating	PMI	Exter. Plating Pb	7439-92-1	0	0	0		
		Exter. Plating Sn	7440-31-5	0.000710025	1000000	25341.72		
		<b>External Plating Total:</b>				<b>0.000710025</b>	<b>1000000</b>	<b>25341.72</b>
		Inter. Plating Ni	7440-02-0	0	0	0		
		Inter. Plating Ag	7440-22-4	8.6E-05	1000000	3069.452		
		<b>Internal Plating Total:</b>				<b>8.6E-05</b>	<b>1000000</b>	<b>3069.452</b>
Die Attach	ELECTRICALLY CONDUCTIVE ADHESIVE	Silver (Ag)	7440-22-4	0.000811	750000	28945.65		
		Tin (Sn)	7440-31-5	0	0	0		
		Lead (Pb)	7439-92-1	0	0	0		
		Silica (SiO2)	60676-86-0	0	0	0		
		Metal Oxide		0	0	0		
		Resin (EP)		0.00027	250000	9636.652		
<b>Die Attach Total:</b>				<b>0.001081</b>	<b>1000000</b>	<b>38582.3</b>		
Encapsulation	MULTI-AROMATIC RESIN Br/Sb FREE	Resin (EP)		0.001659	130000	59211.88		
		Bromine (Br)	40039-93-8	0	0	0		
		Silica (SiO2)	60676-86-0	0.010591	830000	378006.7		
		Antimony Trioxide (Sb2O3)	1309-64-4	0	0	0		
		Metal Hydroxid		0.000447	35000	15954.02		
		Carbon Black (C)	1333-86-4	6.4E-05	5000	2284.244		
		<b>Encapsulation Total:</b>				<b>0.012761</b>	<b>1000000</b>	<b>455456.8</b>
Bond Wire Estimated	AFW/TANAKA/ Kn	Gold (Au)	7440-57-5	0.000151	1000000	5389.388		